

## AD5428/AD5440/AD5447

## Dual 8-/10-/12-Bit, High Bandwidth, Multiplying DACs with Parallel Interface

#### **FEATURES**

- ▶ 10 MHz multiplying bandwidth
- ▶ INL of ±0.25 LSB at 8 bits
- ▶ 20-lead and 24-lead TSSOP packages
- ▶ 2.5 V to 5.5 V supply operation
- ▶ ±10 V reference input
- ▶ 21.3 MSPS update rate
- Extended temperature range: −40°C to +125°C
- ▶ 4-quadrant multiplication
- ▶ Power-on reset
- ▶ 0.5 µA typical current consumption
- Guaranteed monotonic
- Readback function
- ▶ AD7528 upgrade (AD5428)
- ► AD7547 upgrade (AD5447)

#### **APPLICATIONS**

- Portable battery-powered applications
- Waveform generators
- Analog processing
- ▶ Instrumentation applications
- Programmable amplifiers and attenuators
- ▶ Digitally controlled calibration
- Programmable filters and oscillators
- ▶ Composite video
- Ultrasound
- ▶ Gain, offset, and voltage trimming

#### **GENERAL DESCRIPTION**

The AD5428/AD5440/AD5447¹ are CMOS, 8-, 10-, and 12-bit, dual-channel, current output digital-to-analog converters (DACs), respectively. These devices operate from a 2.5 V to 5.5 V power supply, making them suited to battery-powered and other applications.

As a result of being manufactured on a CMOS submicron process, they offer excellent 4-quadrant multiplication characteristics, with large signal multiplying bandwidths of up to 10 MHz.

The DACs use data readback, allowing the user to read the contents of the DAC register via the DB pins. On power-up, the internal register and latches are filled with 0s, and the DAC outputs are at zero scale.

The applied external reference input voltage ( $V_{REF}$ ) determines the full-scale output current. An integrated feedback resistor ( $R_{FB}$ ) provides temperature tracking and full-scale voltage output when combined with an external I-to-V precision amplifier.

The AD5428 is available in a small 20-lead TSSOP package, and the AD5440/AD5447 DACs are available in small 24-lead TSSOP packages.

#### **FUNCTIONAL BLOCK DIAGRAM**

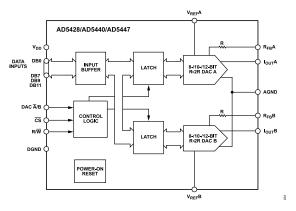


Figure 1.

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<sup>&</sup>lt;sup>1</sup> U.S. Patent Number 5,689,257

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| REVISION HISTORY                              |   |    |
| 1/2025—Rev. D to Rev. E                       |   |    |
| Changes to Table 2 and Figure 2               |   |    |
| Added Resolution and INL Options              |   | 28 |

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## **SPECIFICATIONS**

 $V_{DD}$  = 2.5 V to 5.5 V,  $V_{REF}$  = 10 V,  $I_{OUT}$ 2 = 0 V. Temperature range for Y version: -40°C to +125°C. All specifications  $T_{MIN}$  to  $T_{MAX}$ , unless otherwise noted. DC performance is measured with OP177, and ac performance is measured with AD8038, unless otherwise noted. Guaranteed by Design, Not Subject to Production Test.

Table 1.

| Parameter  | Min                   | Тур | Max   | Unit       | Conditions  |
|--|-----------------------|-----|-------|------------|---|
| STATIC PERFORMANCE   |                       |     |       |            |   |
| AD5428   |                       |     |       |            |   |
| Resolution   |                       |     | 8     | Bits       |   |
| Relative Accuracy  |                       |     | ±0.25 | LSB        |   |
| Differential Nonlinearity  |                       |     | ±1    | LSB        | Guaranteed monotonic  |
| AD5440   |                       |     |       |            |   |
| Resolution   |                       |     | 10    | Bits       |   |
| Relative Accuracy  |                       |     | ±0.5  | LSB        |   |
| Differential Nonlinearity  |                       |     | ±1    | LSB        | Guaranteed monotonic  |
| AD5447   |                       |     |       |            |   |
| Resolution   |                       |     | 12    | Bits       |   |
| Relative Accuracy  |                       |     | ±1    | LSB        |   |
| Differential Nonlinearity  |                       |     | -1/+2 | LSB        | Guaranteed monotonic  |
| Gain Error   |                       |     | ±25   | mV         |   |
| Gain Error Temperature Coefficient                               |                       | ±5  |       | ppm FSR/°C |   |
| Output Leakage Current   |                       | 20  | ±5    | nA         | Data = 0x0000, T <sub>A</sub> = 25°C  |
| output Loundage outront  |                       |     | ±15   | nA         | Data = 0x0000   |
| REFERENCE INPUT  |                       |     | -10   | 11/1       | Data - 0,0000   |
| Reference Input Range  |                       | ±10 |       | V          |   |
| V <sub>REF</sub> A, V <sub>REF</sub> B Input Resistance          | 8                     | 10  | 13    | kΩ         | Input resistance TC = -50 ppm/°C  |
| V <sub>REF</sub> A, V <sub>REF</sub> B Input Resistance Mismatch | 0                     | 1.6 | 2.5   | %          | Typ = 25°C, max = 125°C   |
| Input Capacitance  |                       | 1.0 | 2.3   | /0         | 1yp - 25 G, 11lax - 125 G   |
| Code 0   |                       | 3.5 |       | pF         |   |
| Code 4095  |                       | 3.5 |       | 1 -        |   |
| DIGITAL INPUTS/OUTPUT  |                       | 3.0 |       | pF         |   |
|  | 1.7                   |     |       | V          | V = 26Vto F F V   |
| Input High Voltage, V <sub>IH</sub>                              | 1.7                   |     |       | V          | V <sub>DD</sub> = 3.6 V to 5.5 V  |
| Innut I am Valtage V   | 1.7                   |     | 0.0   | V          | V <sub>DD</sub> = 2.5 V to 3.6 V  |
| Input Low Voltage, V <sub>IL</sub>                               |                       |     | 0.8   | V          | $V_{DD} = 2.7 \text{ V to } 5.5 \text{ V}$  |
| 0 ( (11"   17"   17"   |                       |     | 0.7   | V          | V <sub>DD</sub> = 2.5 V to 2.7 V  |
| Output High Voltage, V <sub>OH</sub>                             | V <sub>DD</sub> - 1   |     |       | V          | $V_{DD} = 4.5 \text{ V to } 5.5 \text{ V, } I_{SOURCE} = 200  \mu\text{A}$                          |
| 0  | V <sub>DD</sub> - 0.5 |     |       | V          | $V_{DD} = 2.5 \text{ V to } 3.6 \text{ V, } I_{SOURCE} = 200  \mu\text{A}$                          |
| Output Low Voltage, V <sub>OL</sub>                              |                       |     | 0.4   | V          | $V_{DD} = 4.5 \text{ V to } 5.5 \text{ V, } I_{SINK} = 200  \mu\text{A}$                            |
|  |                       |     | 0.4   | V .        | V <sub>DD</sub> = 2.5 V to 3.6 V, I <sub>SINK</sub> = 200 μA  |
| Input Leakage Current, I <sub>IL</sub>                           |                       |     | 1     | μA         |   |
| Input Capacitance  |                       | 4   | 10    | pF         |   |
| DYNAMIC PERFORMANCE  |                       |     |       |            |   |
| Reference-Multiplying BW   |                       | 10  |       | MHz        | V <sub>REF</sub> = ±3.5 V p-p, DAC loaded all 1s  |
| Output Voltage Settling Time                                     |                       |     |       |            | $R_{LOAD}$ = 100 Ω, $C_{LOAD}$ = 15 pF, $V_{REF}$ = 10 VDAC latch alternately loaded with 0s and 1s |
| Measured to ±1 mV of FS  |                       | 80  | 120   | ns         |   |
| Measured to ±4 mV of FS  |                       | 35  | 70    | ns         |   |
| Measured to ±16 mV of FS   |                       | 30  | 60    | ns         |   |
| Digital Delay  |                       | 20  | 40    | ns         | Interface delay time  |
| 10% to 90% Settling Time   |                       | 15  | 30    | ns         | Rise and fall times, $V_{REF}$ = 10 V, $R_{LOAD}$ = 100 $\Omega$                                    |
| Digital-to-Analog Glitch Impulse                                 |                       | 3   |       | nV-sec     | 1 LSB change around major carry, V <sub>REF</sub> = 0 V   |

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## **SPECIFICATIONS**

Table 1. (Continued)

| Parameter                                    | Min | Тур | Max | Unit   | Conditions   |
|--|-----|-----|-----|--------|--|
| Multiplying Feedthrough Error                |     |     |     |        | DAC latches loaded with all 0s, V <sub>REF</sub> = ±3.5 V  |
|  |     |     | 70  | dB     | 1 MHz  |
|  |     |     | 48  | dB     | 10 MHz   |
| Output Capacitance                           |     | 12  | 17  | pF     | DAC latches loaded with all 0s   |
|  |     | 25  | 30  | pF     | DAC latches loaded with all 1s   |
| Digital Feedthrough                          |     | 1   |     | nV-sec | Feedthrough to DAC output with $\overline{\text{CS}}$ high andalternate loading of all 0s and all 1s |
| Output Noise Spectral Density                |     | 25  |     | nV/√Hz | @ 1 kHz  |
| Analog THD                                   |     | 81  |     | dB     | V <sub>REF</sub> = 3.5 V p-p, all 1s loaded, f = 100 kHz   |
| Digital THD                                  |     |     |     |        | Clock = 10 MHz, V <sub>REF</sub> = 3.5 V   |
| 100 kHz f <sub>OUT</sub>                     |     | 61  |     | dB     |  |
| 50 kHz f <sub>OUT</sub>                      |     | 66  |     | dB     |  |
| SFDR Performance (Wide Band)                 |     |     |     |        | AD5447, 65k codes, V <sub>REF</sub> = 3.5 V  |
| Clock = 10 MHz                               |     |     |     |        |  |
| 500 kHz f <sub>OUT</sub>                     |     | 55  |     | dB     |  |
| 100 kHz f <sub>OUT</sub>                     |     | 63  |     | dB     |  |
| 50 kHz f <sub>OUT</sub>                      |     | 65  |     | dB     |  |
| Clock = 25 MHz                               |     |     |     |        |  |
| 500 kHz f <sub>OUT</sub>                     |     | 50  |     | dB     |  |
| 100 kHz f <sub>OUT</sub>                     |     | 60  |     | dB     |  |
| 50 kHz f <sub>OUT</sub>                      |     | 62  |     | dB     |  |
| SFDR Performance (Narrow Band)               |     |     |     |        | AD5447, 65k codes, V <sub>REF</sub> = 3.5 V  |
| Clock = 10 MHz                               |     |     |     |        |  |
| 500 kHz f <sub>OUT</sub>                     |     | 73  |     | dB     |  |
| 100 kHz f <sub>OUT</sub>                     |     | 80  |     | dB     |  |
| 50k Hz f <sub>OUT</sub>                      |     | 87  |     | dB     |  |
| Clock = 25 MHz                               |     |     |     |        |  |
| 500 kHz f <sub>OUT</sub>                     |     | 70  |     | dB     |  |
| 100 kHz f <sub>OUT</sub>                     |     | 75  |     | dB     |  |
| 50 kHz f <sub>OUT</sub>                      |     | 80  |     | dB     |  |
| Intermodulation Distortion                   |     |     |     |        | AD5447, 65k codes, V <sub>REF</sub> = 3.5 V  |
| $f_1 = 40 \text{ kHz}, f_2 = 50 \text{ kHz}$ |     | 72  |     | dB     | Clock = 10 MHz   |
| $f_1 = 40 \text{ kHz}, f_2 = 50 \text{ kHz}$ |     | 65  |     | dB     | Clock = 25 MHz   |
| POWER REQUIREMENTS                           |     |     |     |        |  |
| Power Supply Range                           | 2.5 |     | 5.5 | V      |  |
| I <sub>DD</sub>                              |     |     | 0.7 | μA     | T <sub>A</sub> = 25°C, logic inputs = 0 V or V <sub>DD</sub>   |
|  |     | 0.5 | 10  | μA     | $T_A = -40$ °C to +125°C, logic inputs = 0 V or $V_{DD}$   |
| Power Supply Sensitivity                     |     |     |     | %/%    | $\Delta V_{DD} = \pm 5\%$  |

## **TIMING CHARACTERISTICS**

All input signals are specified with tr = tf = 1 ns (10% to 90% of  $V_{DD}$ ) and timed from a voltage level of ( $V_{IL} + V_{IH}$ )/2.  $V_{DD} = 2.5$  V to 5.5 V,  $V_{REF} = 10$  V,  $I_{OUT} = 0$  V, temperature range for Y version:  $-40^{\circ}$ C to  $+125^{\circ}$ C. All specifications  $T_{MIN}$  to  $T_{MAX}$ , unless otherwise noted.

Table 2.

| Parameter <sup>1</sup> | Limit at T <sub>MIN</sub> , T <sub>MAX</sub> | Unit   | Conditions/Comments                           |
|------------------------|--|--------|---|
| Write Mode             |  |        |   |
| t <sub>1</sub>         | 0  | ns min | R/W to CS setup time                          |
| $t_2$                  | 0  | ns min | $R/\overline{W}$ to $\overline{CS}$ hold time |

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## **SPECIFICATIONS**

Table 2. (Continued)

| Parameter <sup>1</sup> | Limit at T <sub>MIN</sub> , T <sub>MAX</sub> | Unit   | Conditions/Comments   |
|------------------------|--|--------|---|
| t <sub>3</sub>         | 10   | ns min | CS low time   |
| $t_4$                  | 10   | ns typ | Address setup time  |
| t <sub>5</sub>         | 10   | ns typ | Address hold time   |
| t <sub>6</sub>         | 6  | ns min | Data setup time   |
| t <sub>7</sub>         | 0  | ns min | Data hold time  |
| t <sub>8</sub>         | 5  | ns min | $R/\overline{W}$ high to $\overline{CS}$ low  |
| t <sub>9</sub>         | 7  | ns min | CS min high time  |
| Data Readback Mode     |  |        |   |
| t <sub>10</sub>        | 0  | ns typ | Address setup time  |
| t <sub>11</sub>        | 0  | ns typ | Address hold time   |
| t <sub>12</sub>        | 5  | ns typ | Data access time  |
|                        | 25   | ns max |   |
| t <sub>13</sub>        | 5  | ns typ | Bus relinquish time   |
|                        | 10   | ns max |   |
| Update Rate            | 21.3   | MSPS   | Consists of $\overline{\text{CS}}$ min high time, $\overline{\text{CS}}$ low time, and output voltage settling time |

<sup>&</sup>lt;sup>1</sup> Guaranteed by design and characterization, not subject to production test.

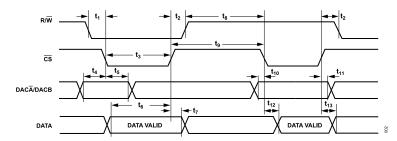


Figure 2. Timing Diagram

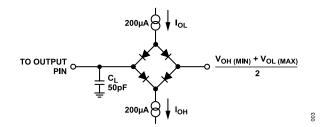


Figure 3. Load Circuit for Data Output Timing Specifications

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#### **ABSOLUTE MAXIMUM RATINGS**

Transient currents of up to 100 mA do not cause SCR latch-up. T<sub>A</sub> = 25°C, unless otherwise noted.

Table 3.

| Parameter   | Rating                                     |
|---|--|
| V <sub>DD</sub> to GND                                  | –0.3 V to +7 V                             |
| $V_{REF}A$ , $V_{REF}B$ , $R_{FB}A$ , $R_{FB}B$ to DGND | -12 V to +12 V                             |
| I <sub>OUT</sub> 1, I <sub>OUT</sub> 2 to DGND          | –0.3 V to +7 V                             |
| Logic Inputs and Output <sup>1</sup>                    | $-0.3 \text{ V to V}_{DD} + 0.3 \text{ V}$ |
| Operating Temperature Range                             |  |
| Automotive (Y Version)                                  | -40°C to +125°C                            |
| Storage Temperature Range                               | -65°C to +150°C                            |
| Junction Temperature                                    | 150°C                                      |
| 20-lead TSSOP θ <sub>JA</sub> Thermal Impedance         | 143°C/W                                    |
| 24-lead TSSOP θ <sub>JA</sub> Thermal Impedance         | 128°C/W                                    |
| Lead Temperature, Soldering (10 sec)                    | 300°C                                      |
| IR Reflow, Peak Temperature (<20 sec)                   | 235°C                                      |

 $<sup>^{1}</sup>$  Overvoltages at DBx,  $\overline{\text{CS}},$  and  $R/\overline{W}$  are clamped by internal diodes.

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

#### **ESD CAUTION**



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

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## PIN CONFIGURATIONS AND FUNCTION DESCRIPTIONS

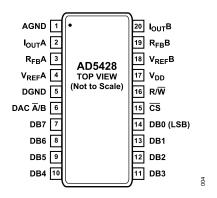


Figure 4. Pin Configuration 20-Lead TSSOP (RU-20)

#### Table 4. AD5428 Pin Function Descriptions

| Pin No. | Mnemonic                               | Description  |
|---------|--|--|
| 1       | AGND                                   | DAC Ground Pin. This pin should typically be tied to the analog ground of the system, but can be biased to achieve single-supply operation.  |
| 2, 20   | I <sub>OUT</sub> A, I <sub>OUT</sub> B | DAC Current Outputs.   |
| 3, 19   | R <sub>FB</sub> A, R <sub>FB</sub> B   | DAC Feedback Resistor Pins. These pins establish voltage output for the DAC by connecting to an external amplifier output.   |
| 4, 18   | $V_{REF}A, V_{REF}B$                   | DAC Reference Voltage Input Terminals.   |
| 5       | DGND                                   | Digital Ground Pin.  |
| 6       | DAC A/B                                | Selects DAC A or DAC B. Low selects DAC A; high selects DAC B.   |
| 7 to14  | DB7 to DB0                             | Parallel Data Bits 7 Through 0.  |
| 15      | CS                                     | Chip Select Input. Active low. Used in conjunction with R/W to load parallel data to the input latch or to read data from the DAC register.  |
| 16      | R/W                                    | Read/Write. When low, used in conjunction with $\overline{\text{CS}}$ to load parallel data. When high, used in conjunction with $\overline{\text{CS}}$ to read back contents of the DAC register. |
| 17      | $V_{DD}$                               | Positive Power Supply Input. This part can be operated from a supply of 2.5 V to 5.5 V.  |

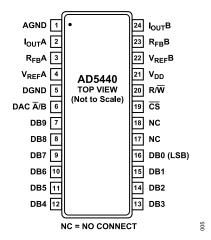


Figure 5. Pin Configuration 24-Lead TSSOP (RU-24)

## Table 5. AD5440 Pin Function Descriptions

| Pin No. | Mnemonic                               | Function  |
|---------|--|---|
| 1       | AGND                                   | DAC Ground Pin. This pin should typically be tied to the analog ground of the system, but can be biased to achieve single-supply operation. |
| 2, 24   | I <sub>OUT</sub> A, I <sub>OUT</sub> B | DAC Current Outputs.  |
| 3, 23   | R <sub>FB</sub> A, R <sub>FB</sub> B   | DAC Feedback Resistor Pins. Establish voltage output for the DAC by connecting to an external amplifier output.                             |
| 4, 22   | V <sub>REF</sub> A, V <sub>REF</sub> B | DAC Reference Voltage Input Terminals.  |
| 5       | DGND                                   | Digital Ground Pin.   |

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## PIN CONFIGURATIONS AND FUNCTION DESCRIPTIONS

#### Table 5. AD5440 Pin Function Descriptions (Continued)

| Pin No. | Mnemonic   | Function   |
|---------|------------|--|
| 6       | DAC A/B    | Selects DAC A or DAC B. Low selects DAC A; high selects DAC B.   |
| 7 to16  | DB9 to DB0 | Parallel Data Bits 9 Through 0.  |
| 19      | CS         | Chip Select Input. Active low. Used in conjunction with R/W to load parallel data to the input latch or to read data from the DAC register.  |
| 20      | R/W        | Read/Write. When low, used in conjunction with $\overline{\text{CS}}$ to load parallel data. When high, used in conjunction with $\overline{\text{CS}}$ to read back contents of the DAC register. |
| 21      | $V_{DD}$   | Positive Power Supply Input. This part can be operated from a supply of 2.5 V to 5.5 V.  |

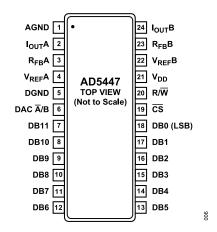


Figure 6. Pin Configuration 24-Lead TSSOP (RU-24)

## Table 6. AD5447 Pin Function Descriptions

| Pin No. | Mnemonic                               | Description   |
|---------|--|---|
| 1       | AGND                                   | DAC Ground Pin. This pin should typically be tied to the analog ground of the system, but can be biased to achieve single-supply operation.   |
| 2, 24   | I <sub>OUT</sub> A, I <sub>OUT</sub> B | DAC Current Outputs.  |
| 3, 23   | R <sub>FB</sub> A, R <sub>FB</sub> B   | DAC Feedback Resistor Pins. Establish voltage output for the DAC by connecting to an external amplifier output.   |
| 4, 22   | V <sub>REF</sub> A, V <sub>REF</sub> B | DAC Reference Voltage Input Terminals.  |
| 5       | DGND                                   | Digital Ground Pin.   |
| 6       | DAC A/B                                | Selects DAC A or DAC B. Low selects DAC A; high selects DAC B.  |
| 7 to 18 | DB11 to DB0                            | Parallel Data Bits 11 Through 0.  |
| 19      | CS                                     | Chip Select Input. Active low. Used in conjunction with R/W to load parallel data to the input latch or to read data from the DAC register.   |
| 20      | R/W                                    | Read/Write. When low, used in conjunction with $\overline{CS}$ to load parallel data. When high, used in conjunction with $\overline{CS}$ to read back the contents of the DAC register. When $\overline{CS}$ and $R/\overline{W}$ are held low, the latches are transparent. Any changes on the data lines are reflected in the relevant DAC output. |
| 21      | $V_{DD}$                               | Positive Power Supply Input. This part can be operated from a supply of 2.5 V to 5.5 V.   |

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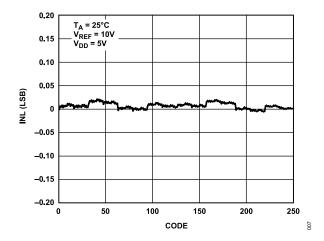


Figure 7. INL vs. Code (8-Bit DAC)

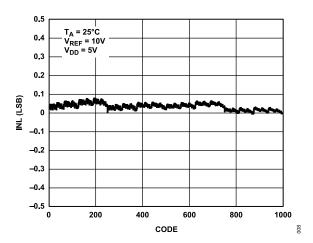


Figure 8. INL vs. Code (10-Bit DAC)

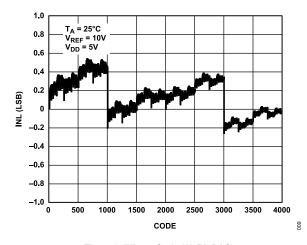


Figure 9. INL vs. Code (12-Bit DAC)

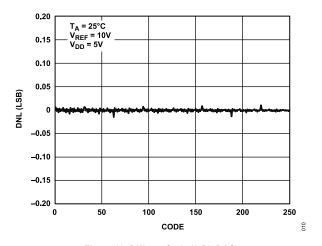


Figure 10. DNL vs. Code (8-Bit DAC)

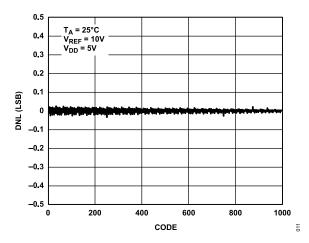


Figure 11. DNL vs. Code (10-Bit DAC)

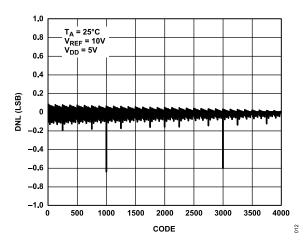


Figure 12. DNL vs. Code (12-Bit DAC)

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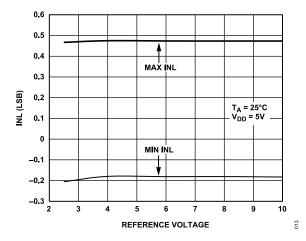


Figure 13. INL vs. Reference Voltage

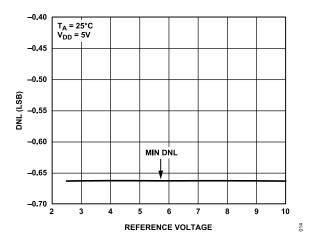


Figure 14. DNL vs. Reference Voltage

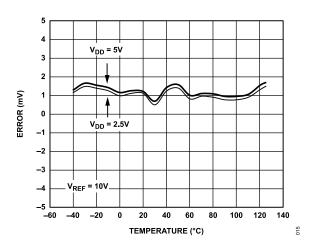


Figure 15. Gain Error vs. Temperature

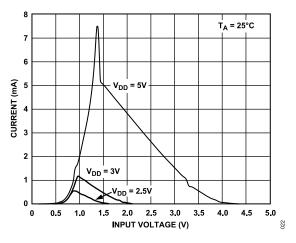


Figure 16. Supply Current vs. Logic Input Voltage

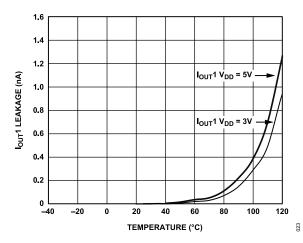


Figure 17. I<sub>OUT</sub>1 Leakage Current vs. Temperature

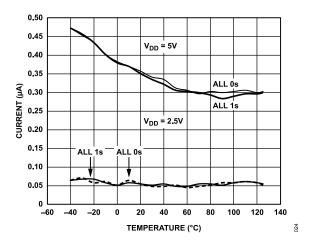


Figure 18. Supply Current vs. Temperature

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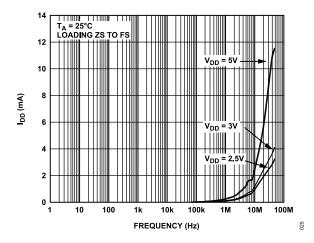


Figure 19. Supply Current vs. Update Rate

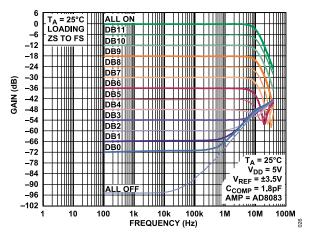


Figure 20. Reference Multiplying Bandwidth vs. Frequency and Code

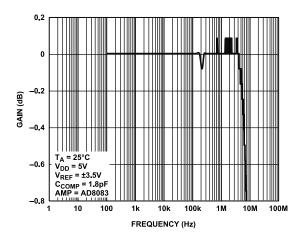


Figure 21. Reference Multiplying Bandwidth—All 1s Loaded

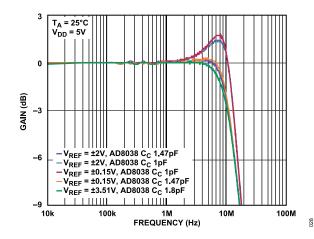


Figure 22. Reference Multiplying Bandwidth vs. Frequency and Compensation Capacitor

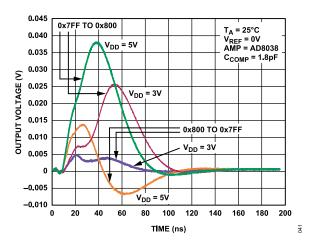


Figure 23. Midscale Transition,  $V_{REF} = 0 V$ 

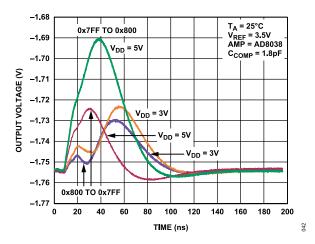


Figure 24. Midscale Transition, V<sub>REF</sub> = 3.5 V

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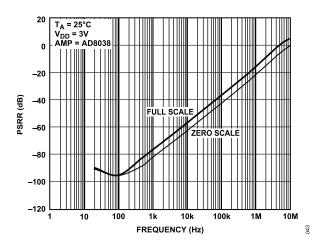


Figure 25. Power Supply Rejection Ratio vs. Frequency

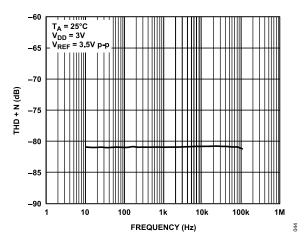


Figure 26. THD + Noise vs. Frequency

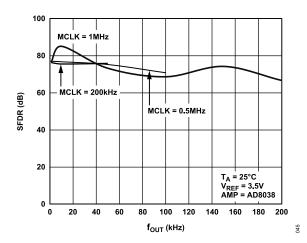


Figure 27. Wideband SFDR vs. f<sub>OUT</sub> Frequency

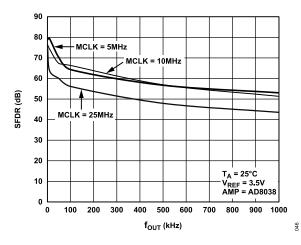


Figure 28. Wideband SFDR vs. f<sub>OUT</sub> Frequency

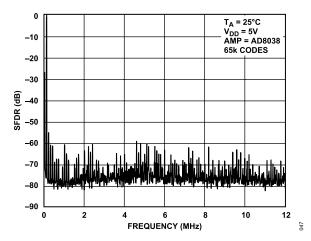


Figure 29. Wideband SFDR,  $f_{OUT} = 100 \text{ kHz}$ , Clock = 25 MHz

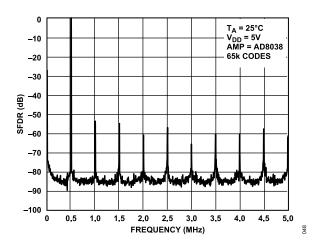


Figure 30. Wideband SFDR, f<sub>OUT</sub> = 500 kHz, Clock = 10 MHz

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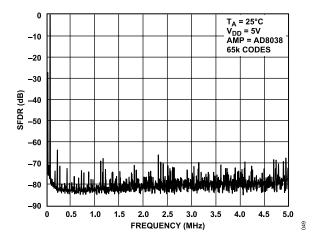


Figure 31. Wideband SFDR, f<sub>OUT</sub> = 50 kHz, Clock = 10 MHz

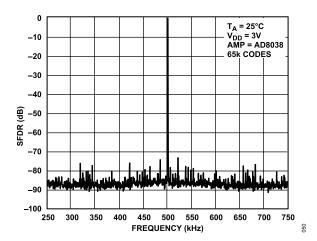


Figure 32. Narrow-Band SFDR,  $f_{OUT}$  = 500 kHz, Clock = 25 MHz

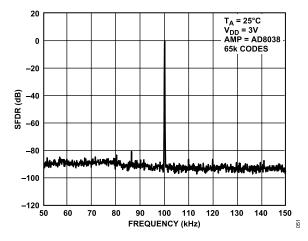


Figure 33. Narrow-Band SFDR,  $f_{OUT}$  = 100 kHz, Clock = 25 MHz

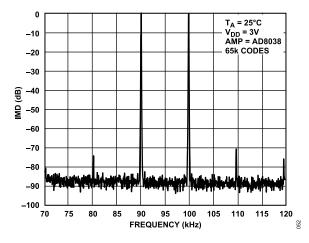


Figure 34. Narrow-Band IMD, f<sub>OUT</sub> = 90 kHz, 100 kHz, Clock = 10 MHz

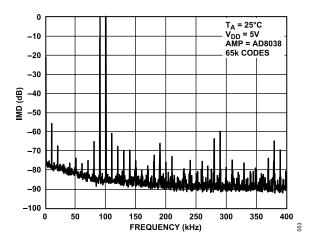


Figure 35. Wideband IMD,  $f_{OUT}$  = 90 kHz, 100 kHz, Clock = 25 MHz

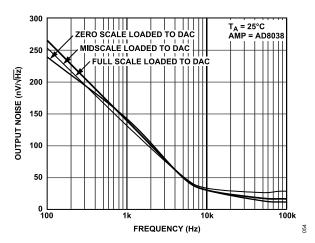


Figure 36. Output Noise Spectral Density

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#### **TERMINOLOGY**

## Relative Accuracy (Endpoint Nonlinearity)

A measure of the maximum deviation from a straight line passing through the endpoints of the DAC transfer function. It is measured after adjusting for zero and full scale and is typically expressed in LSBs or as a percentage of the full-scale reading.

## **Differential Nonlinearity**

The difference in the measured change and the ideal 1 LSB change between two adjacent codes. A specified differential nonlinearity of -1 LSB maximum over the operating temperature range ensures monotonicity.

## Gain Error (Full-Scale Error)

A measure of the output error between an ideal DAC and the actual device output. For these DACs, ideal maximum output is  $V_{REF}-1$  LSB. The gain error of the DACs is adjustable to zero with an external resistance.

## **Output Leakage Current**

The current that flows into the DAC ladder switches when they are turned off. For the  $I_{OUT}$ 1 terminal, it can be measured by loading all 0s to the DAC and measuring the  $I_{OUT}$ 1 current. Minimum current flows into the  $I_{OUT}$ 2 line when the DAC is loaded with all 1s.

## **Output Capacitance**

Capacitance from  $I_{OUT}1$  or  $I_{OUT}2$  to AGND.

#### **Output Current Settling Time**

The amount of time for the output to settle to a specified level for a full-scale input change. For these devices, it is specified with a 100  $\Omega$  resistor to ground.

#### Digital-to-Analog Glitch Impulse

The amount of charge injected from the digital inputs to the analog output when the inputs change state. This is normally specified as the area of the glitch in either pA-sec or nV-sec, depending on whether the glitch is measured as a current or voltage signal.

## **Digital Feedthrough**

When the device is not selected, high frequency logic activity on the device's digital inputs is capacitively coupled through the device and produces noise on the IOUT pins and, subsequently, on the following circuitry. This noise is digital feedthrough.

## Multiplying Feedthrough Error

The error due to capacitive feedthrough from the DAC reference input to the DAC  $I_{OLT}1$  terminal when all 0s are loaded to the DAC.

## **Total Harmonic Distortion (THD)**

The DAC is driven by an ac reference. The ratio of the rms sum of the harmonics of the DAC output to the fundamental value is the THD. Usually only the lower-order harmonics are included, such as second to fifth harmonics.

$$THD = 20\log \frac{\sqrt{V_2^2 + V_3^2 + V_4^2 + V_5^2}}{V_1}$$
 (1)

## **Digital Intermodulation Distortion**

Second-order intermodulation distortion (IMD) measurements are the relative magnitude of the fa and fb tones digitally generated by the DAC and the second-order products at 2fa – fb and 2fb – fa.

## Spurious-Free Dynamic Range (SFDR)

SFDR is the usable dynamic range of a DAC before spurious noise interferes or distorts the fundamental signal. SFDR is the measure of difference in amplitude between the fundamental and the largest harmonic or nonharmonic spur from dc to full Nyquist bandwidth (half the DAC sampling rate, or fs/2). Narrow-band SFDR is a measure of SFDR over an arbitrary window size, in this case 50%, of the fundamental. Digital SFDR is a measure of the usable dynamic range of the DAC when the signal is a digitally generated sine wave.

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#### **DAC SECTION**

The AD5428/AD5440/AD5447 are CMOS 8-, 10-, and 12-bit, dual-channel, current output DACs consisting of a standard inverting R-2R ladder configuration. Figure 37 shows a simplified diagram for a single channel of the 8-bit AD5428. The feedback resistor  $R_{FB}A$  has a value of R. The value of R is typically 10 k $\Omega$  (with a minimum of 8 k $\Omega$  and a maximum of 12 k $\Omega$ ). If  $I_{OUT}1$  and AGND are kept at the same potential, a constant current flows into each ladder leg, regardless of digital input code. Therefore, the input resistance presented at  $V_{REF}A$  is always constant and nominally of value R. The DAC output ( $I_{OUT}$ ) is code-dependent, producing various resistances and capacitances. When choosing an external amplifier, take into account the variation in impedance generated by the DAC on the amplifier's inverting input node.

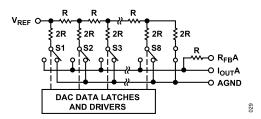


Figure 37. Simplified Ladder

Access is provided to the  $V_{REF}$ ,  $R_{FB}$ , and  $I_{OUT}$  terminals of DAC A and DAC B, making the devices extremely versatile and allowing them to be configured in several operating modes, such as unipolar output mode, 4-quadrant multiplication bipolar mode, or single-supply mode. Note that a matching switch is used in series with the internal  $R_{FB}A$  feedback resistor. If users attempt to measure  $R_{FB}A$ , power must be applied to  $V_{DD}$  to achieve continuity.

#### **CIRCUIT OPERATION**

## **Unipolar Mode**

Using a single op amp, these devices can easily be configured to provide 2-quadrant multiplying operation or a unipolar output

voltage swing, as shown in Figure 38. When an output amplifier is connected in unipolar mode, the output voltage is given by

$$V_{OUT} = -V_{REF} \times D/2^n \tag{2}$$

where:

D is the fractional representation of the digital word loaded to the DAC

D = 0 to 255 (8-bit AD5428)

= 0 to 1023 (10-bit AD5440)

= 0 to 4095 (12-bit AD5447)

n is the resolution of the DAC.

Note that the output voltage polarity is opposite to the  $V_{REF}$  polarity for dc reference voltages. These DACs are designed to operate with either negative or positive reference voltages. The  $V_{DD}$  power pin is only used by the internal digital logic to drive the on and off states of the DAC switches.

These DACs are also designed to accommodate ac reference input signals in the range of –10 V to +10 V.

With a fixed 10 V reference, the circuit in Figure 38 gives a unipolar 0 V to -10 V output voltage swing. When  $V_{IN}$  is an ac signal, the circuit performs 2-quadrant multiplication.

Table 7 shows the relationship between digital code and the expected output voltage for unipolar operation using the 8-bit AD5428.

Table 7. Unipolar Code

| · unio · · · · · · · poi uni · · · · · · · · · · · · · · · · · · · |                                  |  |  |  |  |
|--|----------------------------------|--|--|--|--|
| Digital Input  | Analog Output (V)                |  |  |  |  |
| 1111 1111  | -V <sub>REF</sub> (255/256)      |  |  |  |  |
| 1000 0000  | $-V_{REF}(128/256) = -V_{REF}/2$ |  |  |  |  |
| 0000 0001  | -V <sub>REF</sub> (1/256)        |  |  |  |  |
| 0000 0000  | $-V_{REF}$ (0/256) = 0           |  |  |  |  |

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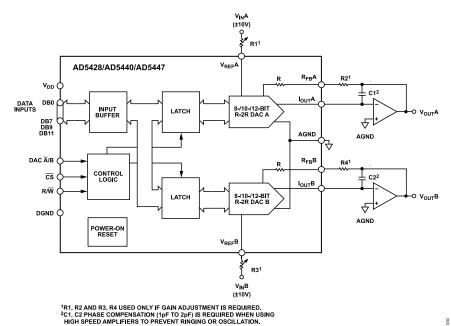


Figure 38. Unipolar Operation

## **Bipolar Operation**

In some applications, it may be necessary to generate full 4-quadrant multiplying operation or a bipolar output swing. This can easily be accomplished by using another external amplifier and some external resistors, as shown in Figure 39. In this circuit, the second amplifier, A2, provides a gain of 2. Biasing the external amplifier with an offset from the reference voltage results in full 4-quadrant multiplying operation. The transfer function of this circuit shows that both negative and positive output voltages are created as the input data (D) is incremented from Code 0 ( $V_{OUT} = -V_{REF}$ ) to midscale ( $V_{OUT} = 0$  V) to full scale ( $V_{OUT} = +V_{REF}$ ). When connected in bipolar mode, the output voltage is given by

$$V_{OUT} = \left(V_{REF} \times D / 2^{n-1}\right) - V_{REF}$$
(3)

#### where:

*D* is the fractional representation of the digital word loaded to the DAC.

D = 0 to 255 (AD5428)

= 0 to 1023 (AD5440)

= 0 to 4095 (AD5447)

n is the number of bits.

When  $V_{\text{IN}}$  is an ac signal, the circuit performs 4-quadrant multiplication. Table 8 shows the relationship between digital code and the expected output voltage for bipolar operation using the 8-bit AD5428.

Table 8. Bipolar Code

| Digital Input | Analog Output (V)           |  |
|---------------|-----------------------------|--|
| 1111 1111     | +V <sub>REF</sub> (127/128) |  |
| 1000 0000     | 0                           |  |
| 0000 0001     | -V <sub>REF</sub> (127/128) |  |
| 0000 0000     | -V <sub>REF</sub> (128/128) |  |

## Stability

In the I-to-V configuration, the  $I_{OUT}$  of the DAC and the inverting node of the op amp must be connected as close as possible, and proper PCB layout techniques must be used. Because every code change corresponds to a step function, gain peaking may occur if the op amp has limited gain bandwidth product (GBP) and there is excessive parasitic capacitance at the inverting node. This parasitic capacitance introduces a pole into the open-loop response, which can cause ringing or instability in the closed-loop applications circuit.

An optional compensation capacitor, C1, can be added in parallel with  $R_{FB}A$  for stability, as shown in Figure 38 and Figure 39. Too small a value of C1 can produce ringing at the output, whereas too large a value can adversely affect the settling time. C1 should be found empirically, but 1 pF to 2 pF is generally adequate for the compensation.

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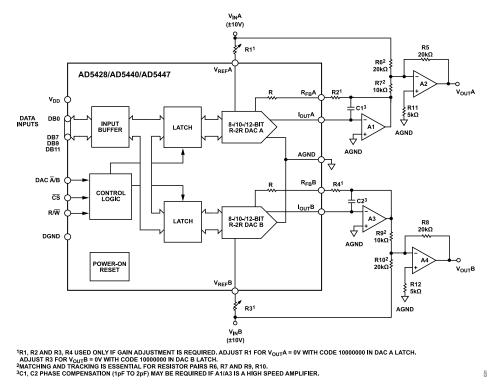


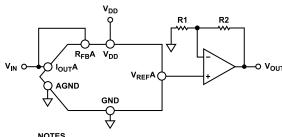
Figure 39. Bipolar Operation (4-Quadrant Multiplication)

#### SINGLE-SUPPLY APPLICATIONS

#### **Voltage-Switching Mode**

Figure 40 shows the DACs operating in voltage switching mode. The reference voltage,  $V_{\text{IN}}$ , is applied to the  $I_{\text{OUT}}A$  pin, and the output voltage is available at the  $V_{\text{REF}}A$  terminal. In this config-uration, a positive reference voltage results in a positive output voltage, making single-supply operation possible. The output from the DAC is voltage at constant impedance (the DAC ladder resistance). Therefore, an op amp is necessary to buffer the output voltage. The reference input no longer sees constant input impedance, but one that varies with code. Therefore, the voltage input should be driven from a low impedance source.

Note that  $V_{\text{IN}}$  is limited to low voltages because the switches in the DAC ladder no longer have the same source-drain drive voltage. As a result, their on resistance differs and degrades the integral linearity of the DAC. Also,  $V_{\text{IN}}$  must not go negative by more than 0.3 V, or an internal diode turns on, causing the device to exceed the maximum ratings. In this type of application, the full range of multiplying capability of the DAC is lost.



- 1. ADDITIONAL PINS OMITTED FOR CLARITY.
- C1 PHASE COMPENSATION (1pf TO 2pf) MAY BE REQUIRED IF A1 IS A HIGH SPEED AMPLIFIER.

Figure 40. Single-Supply Voltage-Switching Mode

## **ADDING GAIN**

In applications where the output voltage must be greater than  $V_{\text{IN}}$ , gain can be added with an additional external amplifier, or it can be achieved in a single stage. Consider the effect of temper-ature coefficients of the thin film resistors of the DAC. Simply placing a resistor in series with the  $R_{\text{FB}}$  resistor causes mismatches in the temperature coefficients, resulting in larger gain temper-ature coefficient errors. Instead, the circuit in Figure 41 shows the recommended method for increasing the gain of the circuit. R1, R2, and R3 must have similar temperature coefficients, but they need not match the temperature coefficients of the DAC. This approach is recommended in circuits where gains of greater than 1 are required. Note that  $R_{\text{FB}} >> R2 ||R3|$  and a gain error percentage of  $100 \times (R2 ||R3)/R_{\text{FB}}$  must be taken into consideration.

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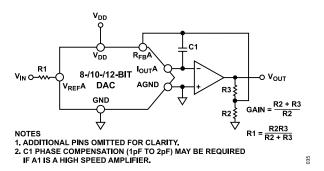


Figure 41. Increasing Gain of Current Output DAC

# DIVIDER OR PROGRAMMABLE GAIN ELEMENT

Current-steering DACs are very flexible and lend themselves to many applications. If this type of DAC is connected as the feedback element of an op amp and  $R_{FB}A$  is used as the input resistor, as shown in Figure 42, the output voltage is inversely proportional to the digital input fraction, D.

For  $D = 1 - 2^{-n}$ , the output voltage is

$$V_{OUT} = -V_{IN}/D = -V_{IN}/(1 - 2^{-n})$$
 (4)

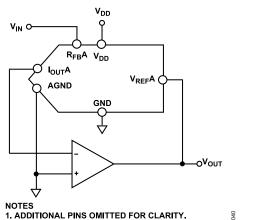


Figure 42. Current-Steering DAC Used as a Divider or Programmable Gain Element

As D is reduced, the output voltage increases. For small values of the digital fraction D, it is important to ensure that the amplifier does not saturate and that the required accuracy is met. For example, an 8-bit DAC driven with the binary code 0x10 (0001 0000)—that is, 16 decimal—in the circuit of Figure 42 should cause the output voltage to be 16 times  $V_{\text{IN}}$ . However, if the DAC has a linearity specification of  $\pm 0.5$  LSB, D can have a weight in the range of 15.5/256 to 16.5/256 so that the possible output voltage is in the range of 15.5  $V_{\text{IN}}$  to 16.5  $V_{\text{IN}}$ —an error of 3%, even though the DAC itself has a maximum error of 0.2%.

DAC leakage current is also a potential error source in divider circuits. The leakage current must be counterbalanced by an opposite current supplied from the op amp through the DAC. Because only

a fraction, D, of the current into the  $V_{REF}$  terminal is routed to the  $I_{OUT}1$  terminal, the output voltage changes as follows:

Output Error Voltage Due to DAC Leakage = (Leakage 
$$\times$$
 R)/D (5)

where R is the DAC resistance at the  $V_{REF}$  terminal.

For a DAC leakage current of 10 nA, R = 10 k $\Omega$ , and a gain (that is, 1/D) of 16, the error voltage is 1.6 mV.

#### REFERENCE SELECTION

When selecting a reference for use with the AD5428/AD5440/ AD5447 series of current output DACs, pay attention to the reference's output voltage temperature coefficient specification. This parameter not only affects the full-scale error, but can also affect the linearity (INL and DNL) performance. The reference temperature coefficient should be consistent with the system accuracy specifications. For example, an 8-bit system required to hold its overall specification to within 1 LSB over the temperature range 0° to 50°C dictates that the maximum system drift with temperature should be less than 78 ppm/°C. A 12-bit system with the same temperature range to overall specification within 2 LSBs requires a maximum drift of 10 ppm/°C. Choosing a precision reference with low output temperature coefficient minimizes this error source. Table 9 lists some references available from Analog Devices that are suitable for use with these current output DACs.

#### **AMPLIFIER SELECTION**

The primary requirement for the current-steering mode is an amplifier with low input bias currents and low input offset voltage. Because of the code-dependent output resistance of the DAC, the input offset voltage of an op amp is multiplied by the variable gain of the circuit. A change in the noise gain between two adjacent digital fractions produces a step change in the output voltage due to the amplifier's input offset voltage. This output voltage change is superimposed on the desired change in output between the two codes and gives rise to a differential linearity error, which, if large enough, could cause the DAC to be nonmonotonic. The input offset voltage should be <1/4 LSB to ensure monotonic behavior when stepping through codes.

The input bias current of an op amp also generates an offset at the voltage output as a result of the bias current flowing in the feedback resistor,  $R_{\text{FB}}$ . Most op amps have input bias currents low enough to prevent significant errors in 12-bit applications.

Common-mode rejection of the op amp is important in voltageswitching circuits, because it produces a code-dependent error at the voltage output of the circuit. Most op amps have adequate common-mode rejection for use at 8-, 10-, and 12-bit resolution.

Provided that the DAC switches are driven from true wideband, low impedance sources ( $V_{\text{IN}}$  and AGND), they settle quickly. Consequently, the slew rate and settling time of a voltage-switching DAC circuit is determined largely by the output op amp. To obtain

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minimum settling time in this configuration, minimize capacitance at the  $V_{REF}$  node (the voltage output node in this application) of the DAC by using low input capacitance buffer amplifiers and careful board design.

Most single-supply circuits include ground as part of the analog signal range, which in turns requires an amplifier that can handle rail-to-rail signals. Analog Devices offers a wide variety of single-supply amplifiers (see Table 10 and Table 11).

Table 9. Suitable ADI Precision References

| Part No. | Output Voltage (V) | Initial Tolerance (%) | Temp Drift (ppm/°C) | I <sub>SS</sub> (mA) | Output Noise (µV p-p) | Package       |
|----------|--------------------|-----------------------|---------------------|----------------------|-----------------------|---------------|
| ADR01    | 10                 | 0.05                  | 3                   | 1                    | 20                    | SOIC-8        |
| ADR01    | 10                 | 0.05                  | 9                   | 1                    | 20                    | TSOT-23, SC70 |
| ADR02    | 5                  | 0.06                  | 3                   | 1                    | 10                    | SOIC-8        |
| ADR02    | 5                  | 0.06                  | 9                   | 1                    | 10                    | TSOT-23, SC70 |
| ADR03    | 2.5                | 0.10                  | 3                   | 1                    | 6                     | SOIC-8        |
| ADR03    | 2.5                | 0.10                  | 9                   | 1                    | 6                     | TSOT-23, SC70 |
| ADR06    | 3                  | 0.10                  | 3                   | 1                    | 10                    | SOIC-8        |
| ADR06    | 3                  | 0.10                  | 9                   | 1                    | 10                    | TSOT-23, SC70 |
| ADR431   | 2.5                | 0.04                  | 3                   | 0.8                  | 3.5                   | SOIC-8        |
| ADR435   | 5                  | 0.04                  | 3                   | 0.8                  | 8                     | SOIC-8        |
| ADR391   | 2.5                | 0.16                  | 9                   | 0.12                 | 5                     | TSOT-23       |
| ADR395   | 5                  | 0.10                  | 9                   | 0.12                 | 8                     | TSOT-23       |

Table 10. Suitable ADI Precision Op Amps

| Part No. | Supply Voltage (V) | V <sub>OS</sub> (Max) (μV) | I <sub>B</sub> (Max) (nA) | 0.1 Hz to 10 Hz Noise (μV p-p) | Supply Current (μA) | Package      |
|----------|--------------------|----------------------------|---------------------------|--------------------------------|---------------------|--------------|
| OP97     | ±2 to ±20          | 25                         | 0.1                       | 0.5                            | 600                 | SOIC-8       |
| OP1177   | ±2.5 to ±15        | 60                         | 2                         | 0.4                            | 500                 | MSOP, SOIC-8 |
| AD8551   | 2.7 to 5           | 5                          | 0.05                      | 1                              | 975                 | MSOP, SOIC-8 |
| AD8603   | 1.8 to 6           | 50                         | 0.001                     | 2.3                            | 50                  | TSOT         |
| AD8628   | 2.7 to 6           | 5                          | 0.1                       | 0.5                            | 850                 | TSOT, SOIC-8 |

Table 11. Suitable ADI High Speed Op Amps

| Part No. | Supply Voltage (V) | BW @ ACL (MHz) | Slew Rate (V/µs) | VOS (Max) (μV) | I <sub>B</sub> (Max) (nA) | Package              |
|----------|--------------------|----------------|------------------|----------------|---------------------------|----------------------|
| AD8065   | 5 to 24            | 145            | 180              | 1,500          | 6,000                     | SOIC-8, SOT-23, MSOP |
| AD8021   | ±2.5 to ±12        | 490            | 120              | 1,000          | 10,500                    | SOIC-8, MSOP         |
| AD8038   | 3 to 12            | 350            | 425              | 3,000          | 750                       | SOIC-8, SC70-5       |
| AD9631   | ±3 to ±6           | 320            | 1,300            | 10,000         | 7,000                     | SOIC-8               |

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#### PARALLEL INTERFACE

Data is loaded into the AD5428/AD5440/AD5447 in 8-, 10-, or 12-bit parallel word format. Control lines  $\overline{CS}$  and R/W allow data to be written to or read from the DAC register. A write event takes place when  $\overline{CS}$  and R/W are brought low, data available on the data lines fills the shift register, and the rising edge of  $\overline{CS}$  latches the data and transfers the latched data-word to the DAC register. The DAC latches are not transparent; therefore, a write sequence must consist of a falling and rising edge on  $\overline{CS}$  to ensure that data is loaded into the DAC register and its analog equivalent is reflected on the DAC output.

A read event takes place when  $R/\overline{W}$  is held high and  $\overline{CS}$  is brought low. Data is loaded from the DAC register, goes back into the input register, and is output onto the data line, where it can be read back to the controller for verification or diagnostic purposes. The input and DAC registers of these devices are not transparent; therefore, a falling and rising edge of  $\overline{CS}$  is required to load each data-word.

#### MICROPROCESSOR INTERFACING

## ADSP-2191M and Family to AD5428/AD5440/ AD5447 Interface

Figure 43 shows the AD5428/AD5440/AD5447 interfaced to the ADSP-2191M series of DSPs as a memory-mapped device. A single wait state may be necessary to interface the AD5428/AD5440/AD5447 to the ADSP-2191M, depending on the clock speed of the DSP. The wait state can be programmed via the data memory wait state control register of the ADSP-2191M (see the ADSP-2191M family user manual for details).

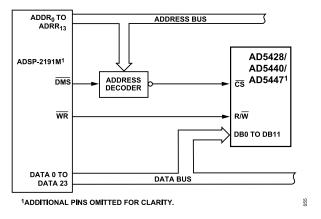


Figure 43. ADSP-2191M-to-AD5428/AD5440/AD5447 Interface

## 8xC51-to-AD5428/AD5440/AD5447 Interface

Figure 44 shows the interface between the AD5428/AD5440/ AD5447 and the 8xC51 family of DSPs. To facilitate external data memory access, the address latch enable (ALE) mode is enabled. The low byte of the address is latched with this output pulse during access to the external memory. AD0 to AD7 are the multiplexed low order addresses and data bus, and they require strong internal

pull-ups when emitting 1s. During access to external memory, A8 to A15 are the high order address bytes. Because these ports are open drain, they also require strong internal pull-ups when emitting 1s

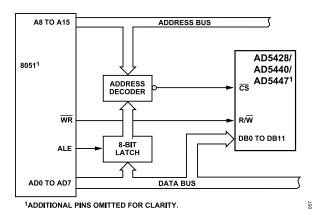


Figure 44. 8xC51-to-AD5428/AD5440/AD5447 Interface

## ADSP-BF534 to AD5428/AD5440/AD5447 Interface

Figure 45 shows a typical interface between the AD5428/AD5440/ AD5447 and the ADSP-BF534 family of DSPs. The asynchronous memory write cycle of the processor drives the digital inputs of the DAC. The  $\overline{\text{AMS}}$ x line is actually four memory select lines. Internal ADDR lines are decoded into  $\overline{\text{AMS}}_{3-0}$ , and then these lines are inserted as chip selects. The rest of the interface is a standard handshaking operation.

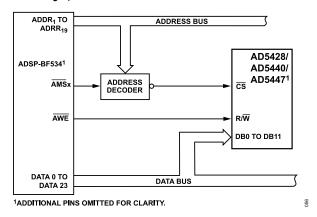


Figure 45. ADSP-BF534-to-AD5428/AD5440/AD5447 Interface

# PCB LAYOUT AND POWER SUPPLY DECOUPLING

In any circuit where accuracy is important, careful consideration of the power supply and ground return layout helps to ensure the rated performance. The printed circuit board on which the AD5428/AD5440/AD5447 is mounted should be designed so that the analog and digital sections are separate and confined to certain areas of the board. If the DAC is in a system where multiple devices require an AGND-to-DGND connection, the connection should be made

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at one point only. The star ground point should be established as close as possible to the device.

These DACs should have ample supply bypassing of 10  $\mu F$  in parallel with 0.1  $\mu F$  on the supply located as close as possible to the package, ideally right up against the device. The 0.1  $\mu F$  capacitor should have low effective series resistance (ESR) and low effective series inductance (ESI), like the common ceramic types of capacitors that provide a low impedance path to ground at high frequencies, to handle transient currents due to internal logic switching. Low ESR 1  $\mu F$  to 10  $\mu F$  tantalum or electrolytic capacitors should also be applied at the supplies to minimize transient disturbance and filter out low frequency ripple.

Components, such as clocks, that produce fast-switching signals should be shielded with digital ground to avoid radiating noise to other parts of the board, and they should never be run near the reference inputs.

Avoid crossover of digital and analog signals. Traces on opposite sides of the board should run at right angles to each other. This reduces the effects of feedthrough on the board. A microstrip technique is by far the best method, but its use is not always possible with a double-sided board. In this technique, the component side of the board is dedicated to the ground plane, and signal traces are placed on the soldered side.

It is good practice to use compact, minimum lead length PCB layout design. Leads to the input should be as short as possible to minimize IR drops and stray inductance.

The PCB metal traces between  $V_{REF}$  and  $R_{FB}$  should also be matched to minimize gain error. To maximize high frequency performance, the I-to-V amplifier should be located as close as possible to the device.

#### **EVALUATION BOARD FOR THE AD5447**

The evaluation board consists of an AD5447 DAC and a current-to-voltage amplifier, the AD8065. Included on the evaluation board is a 10 V reference, the ADR01. An external reference may also be applied via an SMB input.

The evaluation kit consists of a CD-ROM with self-installing PC software to control the DAC. The software simply allows the user to write a code to the device.

# POWER SUPPLIES FOR THE EVALUATION BOARD

The board requires  $\pm 12$  V and  $\pm 5$  V supplies. The  $\pm 12$  V V<sub>DD</sub> and  $\pm 12$  V V<sub>SS</sub> are used to power the output amplifier; the  $\pm 5$  V is used to power the DAC (V<sub>DD1</sub>) and transceivers (V<sub>CC</sub>).

Both supplies are decoupled to their respective ground plane with  $10 \mu$ F tantalum and  $0.1 \mu$ F ceramic capacitors.

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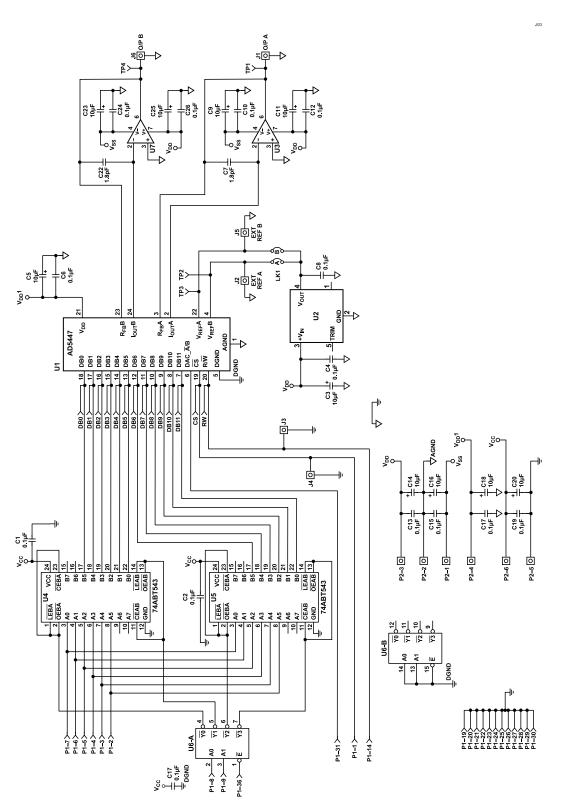


Figure 46. Schematic of AD5447 Evaluation Board

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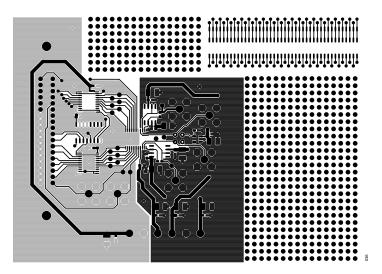


Figure 47. Component-Side Artwork

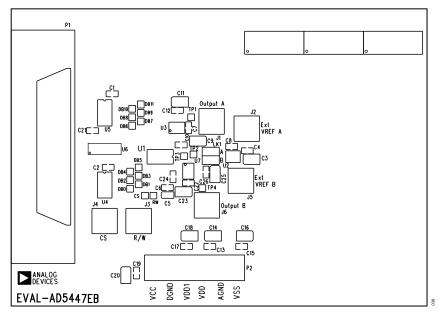


Figure 48. Silkscreen—Component-Side View (Top Layer)

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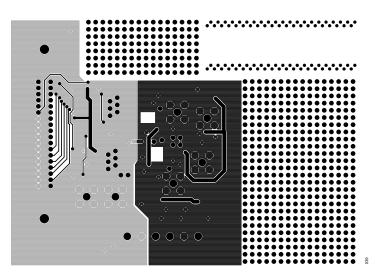


Figure 49. Solder-Side Artwork

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## **BILL OF MATERIALS**

Table 12. Bill of Materials

| Name/Position   | Part Description              | Value       | Tolerance (%) | Stock Code                  |
|-----------------|-------------------------------|-------------|---------------|-----------------------------|
| C1              | X7R ceramic capacitor         | 0.1 μF      | 10            | FEC 499-675                 |
| C2              | X7R ceramic capacitor         | 0.1 μF      | 10            | FEC 499-675                 |
| C3              | Tantalum capacitor—Taj series | 10 μF, 20 V | 10            | FEC 197-427                 |
| C4              | X7R ceramic capacitor         | 0.1 μF      | 10            | FEC 499-675                 |
| C5              | Tantalum capacitor—Taj series | 10 μF, 10 V | 10            | FEC 197-130                 |
| C6              | X7R ceramic capacitor         | 0.1 μF      | 10            | FEC 499-675                 |
| C7              | NPO ceramic capacitor         | 1.8 pF      | 10            | FEC 721-876                 |
| C8              | X7R ceramic capacitor         | 0.1 μF      | 10            | FEC 499-675                 |
| C9              | Tantalum capacitor—Taj series | 10 μF, 20 V | 10            | FEC 197-427                 |
| C10             | X7R ceramic capacitor         | 0.1 μF      | 10            | FEC 499-675                 |
| C11             | Tantalum capacitor—Taj series | 10 μF, 20 V | 10            | FEC 197-427                 |
| C12             | X7R ceramic capacitor         | 0.1 µF      | 10            | FEC 499-675                 |
| C13             | X7R ceramic capacitor         | 0.1 µF      | 10            | FEC 499-675                 |
| C14             | Tantalum capacitor—Taj series | 10 μF, 20 V | 10            | FEC 197-427                 |
| C15             | X7R ceramic capacitor         | 0.1 µF      | 10            | FEC 499-675                 |
| C16             | Tantalum capacitor—Taj series | 10 μF, 20 V | 10            | FEC 197-427                 |
| C17             | X7R ceramic capacitor         | 0.1 µF      | 10            | FEC 499-675                 |
| C18             | Tantalum capacitor—Taj series | 10 μF, 20 V | 10            | FEC 197-427                 |
| C19             | X7R ceramic capacitor         | 0.1 µF      | 10            | FEC 499-675                 |
| C20             | Tantalum capacitor—Taj series | 10 μF, 20 V | 10            | FEC 197-427                 |
| C21             | X7R ceramic capacitor         | 0.1 µF      | 10            | FEC 499-675                 |
| C22             | NPO ceramic capacitor         | 1.8 pF      | 10            | FEC 721-876                 |
| C23             | Tantalum capacitor—Taj series | 10 μF, 20 V | 10            | FEC 197-427                 |
| C24             | X7R ceramic capacitor         | 0.1 µF      | 10            | FEC 499-675                 |
| C25             | Tantalum capacitor—Taj series | 10 μF, 20 V | 10            | FEC 197-427                 |
| C26             | X7R ceramic capacitor         | 0.1 µF      | 10            | FEC 499-675                 |
| CS, DB0 to DB11 | Red testpoint                 | ,           |               | FEC 240-345 (Pack)          |
| J1 to J6        | SMB socket                    |             |               | FEC 310-682                 |
| J2              | SMB socket                    |             |               | FEC 310-682                 |
| J3              | SMB socket                    |             |               | FEC 310-682                 |
| J4              | SMB socket                    |             |               | FEC 310-682                 |
| J5              | SMB socket                    |             |               | FEC 310-682                 |
| J6              | SMB socket                    |             |               | FEC 310-682                 |
| LK1             | 3-pin header (2 × 2)          |             |               | FEC 511-791 and FEC 528-456 |
| P1              | 36-pin Centronics connector   |             |               | FEC 147-753                 |
| P2              | 6-pin terminal block          |             |               | FEC 151-792                 |
| RW              | Red testpoint                 |             |               | FEC 240-345 (Pack)          |
| TP1 to TP4      | Red testpoint                 |             |               | FEC 240-345 (Pack)          |
| U1              | AD5447                        |             |               | AD5447YRU                   |
| U2              | ADR01                         |             |               | ADR01AR                     |
| U3              | AD8065                        |             |               | AD8065AR                    |
| U4, U5          | 74ABT543                      |             |               | Fairchild 74ABT543CMTC      |
| U6              | 74139                         |             |               | CD74HCT139M                 |
| U7              | AD8065                        |             |               | AD8065AR                    |
| Each Corner     | Rubber stick-on feet          |             |               | FEC 148-922                 |

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## **OVERVIEW OF MULTIPLYING DAC DEVICES**

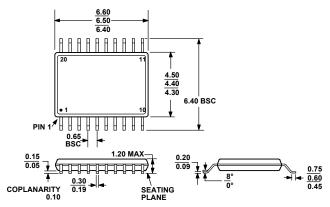
Table 13.

| Part No. | Resolution | No. DACs | INL (LSB) | Interface | Package <sup>1</sup> | Features                        |
|----------|------------|----------|-----------|-----------|----------------------|---------------------------------|
| AD5424   | 8          | 1        | ±0.25     | Parallel  | RU-16, CP-20         | 10 MHz BW, 17 ns CS pulse width |
| AD5426   | 8          | 1        | ±0.25     | Serial    | RM-10                | 10 MHz BW, 50 MHz serial        |
| AD5428   | 8          | 2        | ±0.25     | Parallel  | RU-20                | 10 MHz BW, 17 ns CS pulse width |
| AD5429   | 8          | 2        | ±0.25     | Serial    | RU-10                | 10 MHz BW, 50 MHz serial        |
| AD5450   | 8          | 1        | ±0.25     | Serial    | UJ-8                 | 10 MHz BW, 50 MHz serial        |
| AD5432   | 10         | 1        | ±0.5      | Serial    | RM-10                | 10 MHz BW, 50 MHz serial        |
| AD5433   | 10         | 1        | ±0.5      | Parallel  | RU-20, CP-20         | 10 MHz BW, 17 ns CS pulse width |
| AD5439   | 10         | 2        | ±0.5      | Serial    | RU-16                | 10 MHz BW, 50 MHz serial        |
| AD5440   | 10         | 2        | ±0.5      | Parallel  | RU-24                | 10 MHz BW, 17 ns CS pulse width |
| AD5451   | 10         | 1        | ±0.25     | Serial    | UJ-8                 | 10 MHz BW, 50 MHz serial        |
| AD5443   | 12         | 1        | ±1        | Serial    | RM-10                | 10 MHz BW, 50 MHz serial        |
| AD5444   | 12         | 1        | ±0.5      | Serial    | RM-8                 | 10 MHz BW, 50 MHz serial        |
| AD5415   | 12         | 2        | ±1        | Serial    | RU-24                | 10 MHz BW, 50 MHz serial        |
| AD5405   | 12         | 2        | ±1        | Parallel  | CP-40                | 10 MHz BW, 17 ns CS pulse width |
| AD5445   | 12         | 2        | ±1        | Parallel  | RU-20, CP-20         | 10 MHz BW, 17 ns CS pulse width |
| AD5447   | 12         | 2        | ±1        | Parallel  | RU-24                | 10 MHz BW, 17 ns CS pulse width |
| AD5449   | 12         | 2        | ±1        | Serial    | RU-16                | 10 MHz BW, 50 MHz serial        |
| AD5452   | 12         | 1        | ±0.5      | Serial    | UJ-8, RM-8           | 10 MHz BW, 50 MHz serial        |
| AD5446   | 14         | 1        | ±1        | Serial    | RM-8                 | 10 MHz BW, 50 MHz serial        |
| AD5453   | 14         | 1        | ±2        | Serial    | UJ-8, RM-8           | 10 MHz BW, 50 MHz serial        |
| AD5553   | 14         | 1        | ±1        | Serial    | RM-8                 | 4 MHz BW, 50 MHz serial clock   |
| AD5556   | 14         | 1        | ±1        | Parallel  | RU-28                | 4 MHz BW, 20 ns WR pulse width  |
| AD5555   | 14         | 2        | ±1        | Serial    | RM-8                 | 4 MHz BW, 50 MHz serial clock   |
| AD5557   | 14         | 2        | ±1        | Parallel  | RU-38                | 4 MHz BW, 20 ns WR pulse width  |
| AD5543   | 16         | 1        | ±2        | Serial    | RM-8                 | 4 MHz BW, 50 MHz serial clock   |
| AD5546   | 16         | 1        | ±2        | Parallel  | RU-28                | 4 MHz BW, 20 ns WR pulse width  |
| AD5545   | 16         | 2        | ±2        | Serial    | RU-16                | 4 MHz BW, 50 MHz serial clock   |
| AD5547   | 16         | 2        | ±2        | Parallel  | RU-38                | 4 MHz BW, 20 ns WR pulse width  |

<sup>&</sup>lt;sup>1</sup> RU = TSSOP, CP = LFCSP, RM = MSOP, UJ = TSOT.

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#### **OUTLINE DIMENSIONS**



COMPLIANT TO JEDEC STANDARDS MO-153-AC

Figure 50. 20-Lead Thin Shrink Small Outline Package [TSSOP] (RU-20) Dimensions shown in millimeters

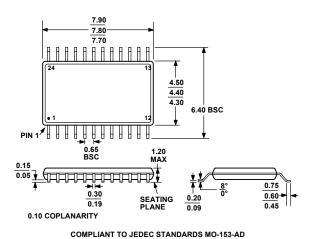


Figure 51. 24-Lead Thin Shrink Small Outline Package [TSSOP] (RU-24)

Dimensions shown in millimeters

## **ORDERING GUIDE**

| Model <sup>1</sup> | Temperature Range | Package Description | Package Option |
|--------------------|-------------------|---------------------|----------------|
| AD5428YRU          | -40°C to +125°C   | 20-Lead TSSOP       | RU-20          |
| AD5428YRU-REEL7    | -40°C to +125°C   | 20-Lead TSSOP       | RU-20          |
| AD5428YRUZ         | -40°C to +125°C   | 20-Lead TSSOP       | RU-20          |
| AD5428YRUZ-REEL    | -40°C to +125°C   | 20-Lead TSSOP       | RU-20          |
| AD5428YRUZ-REEL7   | -40°C to +125°C   | 20-Lead TSSOP       | RU-20          |
| AD5440YRU          | -40°C to +125°C   | 24-Lead TSSOP       | RU-24          |
| AD5440YRUZ         | -40°C to +125°C   | 24-Lead TSSOP       | RU-24          |
| AD5440YRUZ-REEL    | -40°C to +125°C   | 24-Lead TSSOP       | RU-24          |
| AD5440YRUZ-REEL7   | -40°C to +125°C   | 24-Lead TSSOP       | RU-24          |
| AD5447YRU          | -40°C to +125°C   | 24-Lead TSSOP       | RU-24          |
| AD5447YRUZ         | -40°C to +125°C   | 24-Lead TSSOP       | RU-24          |

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## **OUTLINE DIMENSIONS**

| Model <sup>1</sup> | Temperature Range | Package Description | Package Option |
|--------------------|-------------------|---------------------|----------------|
| AD5447YRUZ-REEL    | -40°C to +125°C   | 24-Lead TSSOP       | RU-24          |
| AD5447YRUZ-REEL7   | -40°C to +125°C   | 24-Lead TSSOP       | RU-24          |

<sup>&</sup>lt;sup>1</sup> Z = RoHS Compliant Part.

## **RESOLUTION AND INL OPTIONS**

| Model <sup>1</sup> | Resolution | INL (LSB) |  |
|--------------------|------------|-----------|--|
| AD5428YRU          | 8          | ±0.5      |  |
| AD5428YRU-REEL7    | 8          | ±0.5      |  |
| AD5428YRUZ         | 8          | ±0.5      |  |
| AD5428YRUZ-REEL    | 8          | ±0.5      |  |
| AD5428YRUZ-REEL7   | 8          | ±0.5      |  |
| AD5440YRU          | 10         | ±0.5      |  |
| AD5440YRUZ         | 10         | ±0.5      |  |
| AD5440YRUZ-REEL    | 12         | ±1        |  |
| AD5440YRUZ-REEL7   | 12         | ±1        |  |
| AD5447YRU          | 12         | ±1        |  |
| AD5447YRUZ         | 12         | ±1        |  |
| AD5447YRUZ-REEL    | 12         | ±1        |  |
| AD5447YRUZ-REEL7   | 12         | ±1        |  |

<sup>&</sup>lt;sup>1</sup> Z = RoHS Compliant Part.

## **EVALUATION BOARDS**

| Model <sup>1</sup> | Package Description |
|--------------------|---------------------|
| EVAL-AD5447EBZ     | Evaluation Kit      |

<sup>&</sup>lt;sup>1</sup> Z = RoHS Compliant Part.



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